Date: October 27, 2025

To

Listing Compliance Department	**Listing Compliance Department**
M/s. BSE Limited	**M/s. National Stock Exchange of India Limited**
Phiroze Jeejeebhoy Towers	Exchange Plaza, 5th Floor, Plot No. C/1, G Block, Bandra
Dalal Street	Kurla Complex, Bandra (E),
Mumbai- 400001	Mumbai 400 051
Scrip code: 532850	**Scrip Symbol: MICEL**

Dear Sir/Madam,

Subject: Memorandum of Understanding – Regulation 30 of SEBI (LODR) Regulations, 2015.

Pursuant to Regulation 30 and other applicable regulations of the Securities and Exchange Board of India (Listing Obligations and Disclosure Requirements) Regulations, 2015 ('Listing Regulations'), we wish to inform you that **M/s. MIC Electronics Limited ("MIC") ("OEM Partner")** has entered a MOU (Memorandum of Understanding) with **M/s. Chipex Technologies Private Limited ("Chipex") ("Chip Development Partner")**

The Memorandum of Understanding establishes a collaborative framework between **Chipex** and **MIC** to jointly develop custom semiconductor solutions aligned with **MIC's** product roadmap. Through this partnership, **MIC** aims to enhance product differentiation, performance, and long-term supply stability by using co-developed custom silicon instead of standard components.

Additional Details are enclosed in Annexure-A.

Kindly take the same on the record

Thanking you
For MIC Electronics Limited

LAKSHMI SOWJANYA ALLA

Digitally signed by LAKSHMI SOWJANYA ALLA
Date: 2025.10.27 11:06:09 +05'30'

MIC Electronics Limited Hyd

Lakshmi Sowjanya Alla
Company Secretary & Compliance Officer

Encl: A/a.

Annexure-A

Additional Details:

a.	Name(s) of parties with whom the agreement is entered	**M/s. Chipex Technologies Private Limited**
b.	Purpose of entering into the agreement	The purpose of this Memorandum of Understanding ("MoU") is to establish a strategic and collaborative framework between **CHIPEX** ("Chip Development Partner") and **MIC** ("OEM Partner") for the joint identification, definition, design, and development of **custom semiconductor solutions** that align with and support MIC ELECTRONICS's product roadmap. Through this collaboration, the Parties intend to combine their respective technical expertise and domain experience to co-create silicon solutions tailored to the unique performance, functionality, and integration requirements of MIC ELECTRONICS's product portfolio. By leveraging **co-developed custom silicon** rather than standard off-the-shelf components, MIC ELECTRONICS aims to achieve: **Enhanced product differentiation** through proprietary and optimized chip architectures. **Improved system performance** and energy efficiency across its application domains. **Long-term supply assurance** and design ownership, ensuring sustainability and competitiveness in global markets. This MoU outlines the guiding principles for collaboration and serves as a foundation for subsequent **Statements of Work (SOWs)** that will define project-specific deliverables, commercial terms, and responsibilities of each Party.
c.	Shareholding, if any, in the entity with whom the agreement is executed;	Nil
d.	Significant terms of the agreement (in brief) special rights like right to appoint directors, first right to share subscription in case of issuance of shares, right to restrict any change in capital structure etc	Nil

e.	Whether, the said parties are related to promoter/promoter group/ group companies in any manner. If yes, nature of relationship;	No
f.	Whether the transaction would fall within related party transactions? If yes, whether the same is done at "arm's length";	No
g.	In case of issuance of shares to the parties, details of issue price, class of shares issued;	NA
h.	Any other disclosures related to such agreements, viz., details of nominee on the board of directors of the listed entity, potential conflict of interest arising out of such agreements, etc.;	
I.	In case of termination or amendment of agreement, listed entity shall disclose additional details to the stock exchange(s): a) name of parties to the agreement; b) nature of the agreement; c) date of execution of the agreement; d) details of amendment and impact thereof or reasons of termination and impact thereof.	